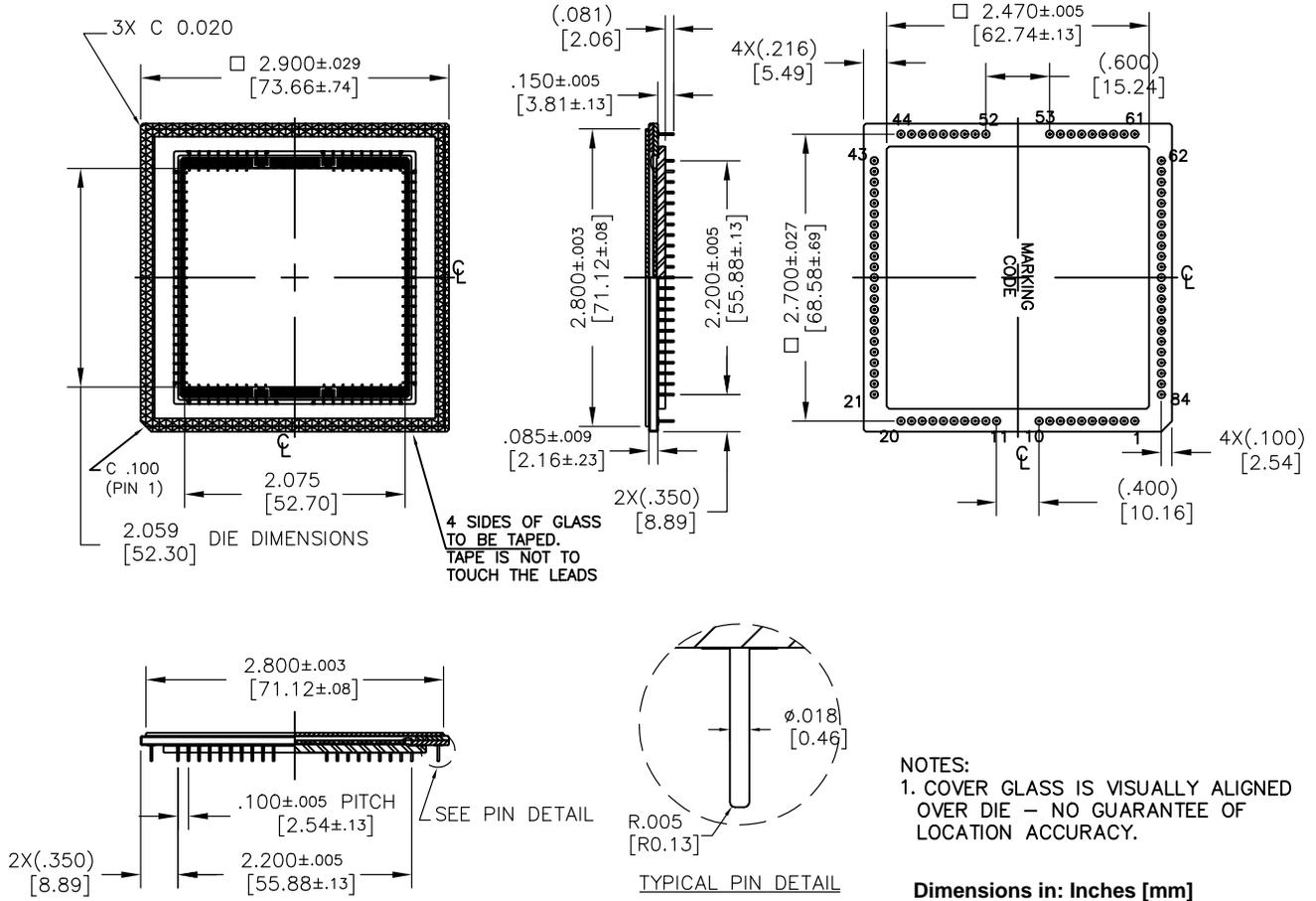


MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

CPGA84, 73.66x73.66
CASE 107EU
ISSUE O

DATE 30 JUL 2014



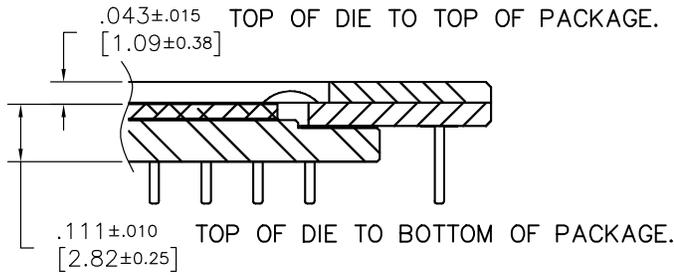
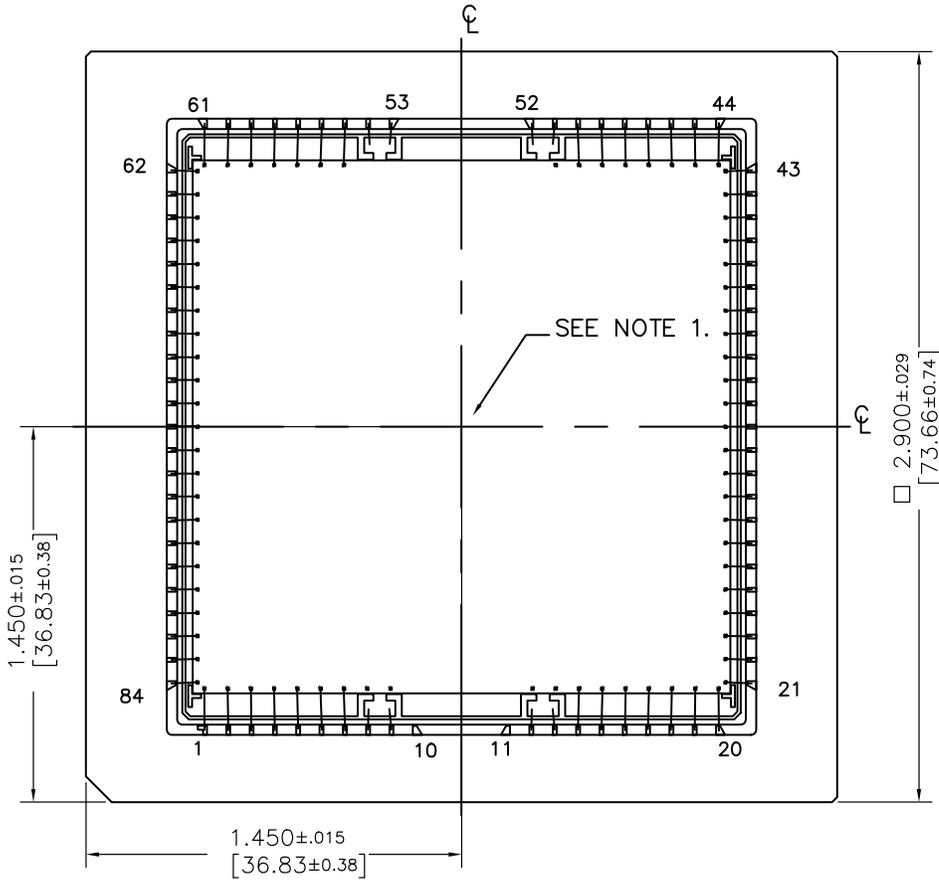
NOTES:
 1. COVER GLASS IS VISUALLY ALIGNED OVER DIE – NO GUARANTEE OF LOCATION ACCURACY.

Dimensions in: Inches [mm]

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CPGA84, 73.66x73.66
CASE 107EU
ISSUE O

DATE 30 JUL 2014



Dimensions in: Inches [mm]

NOTES:

1. CENTER OF IMAGE AREA IS OFFSET FROM CENTER OF PACKAGE BY (0.00, -0.00)mm NOMINAL.
2. DIE IS VISUALLY ALIGNED WITHIN $\pm 2^\circ$ OF ANY PACKAGE CAVITY EDGE.

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